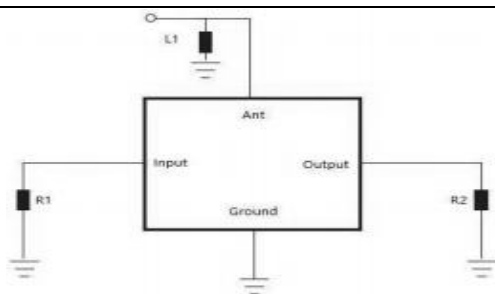


(746-756)	30-30	dB	36	41	-
	699.25-715.75	dB	32	50	-
	716-722	dB	45	50	-
	776-793	dB	30	36	-
	793-805	dB	30	36	-
	824-849	dB	40	45	-
	1710-1755	dB	40	45	-
	1850-1920	dB	40	46	-
	2187-2238	dB	30	36	-
	2400-2500	dB	42	50	-
	4900-5950	dB	36	41	-
Isolation	746-756	dB	55	63	-
	777-787	dB	55	60	-
Operation Temperature	-20°C~+85°C	°C	-	-	-
Storage Temperature	-40°C~+85°C	°C	-	-	-
RF Power Dissipation	+29	dBm	-	-	-
Remark	Note 1: Test Temperature: 25°C±2°C				
	Note 2: Terminating source impedance: 50Ω. Terminating load impedance: 50Ω				

(3)Test Circuit



Port	Matching Component
Tx	R1: 50Ω
Rx	R2: 50Ω
Ant	L1 : 11.6 nH (Ideal inductor)

Figure 1 Electrical Characteristics: Tx to Ant.

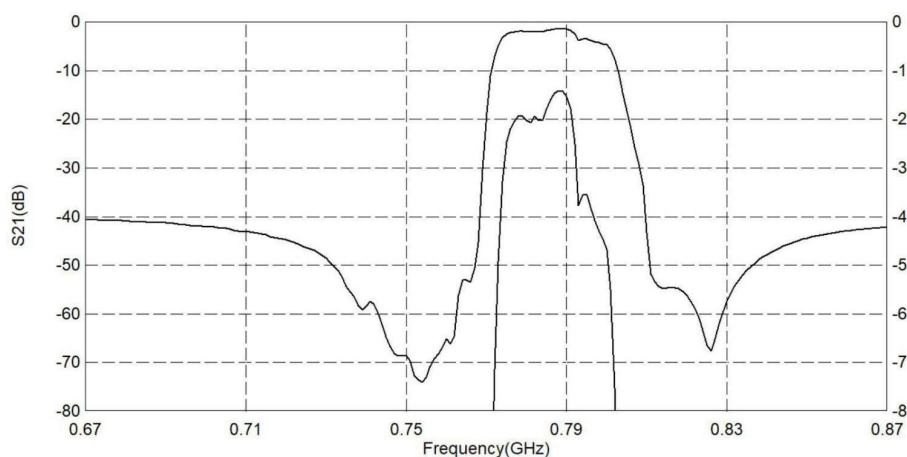


Figure 2 Electrical Characteristics: Tx to Ant.

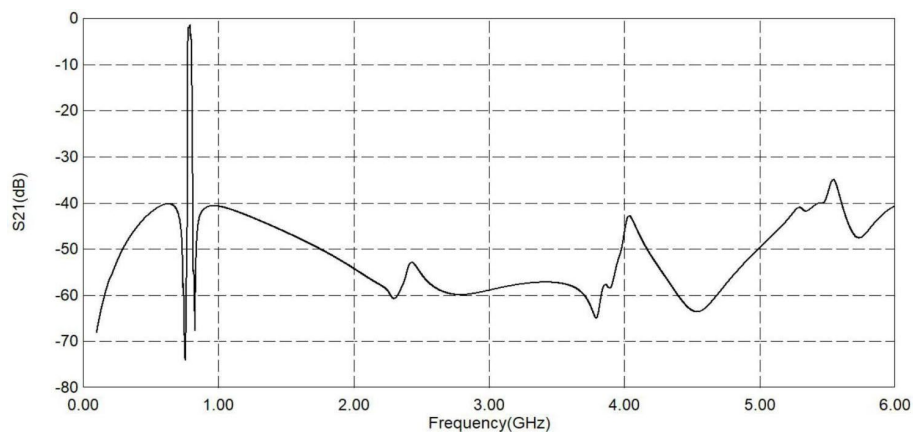


Figure 3 Electrical Characteristics: Ant to Rx.

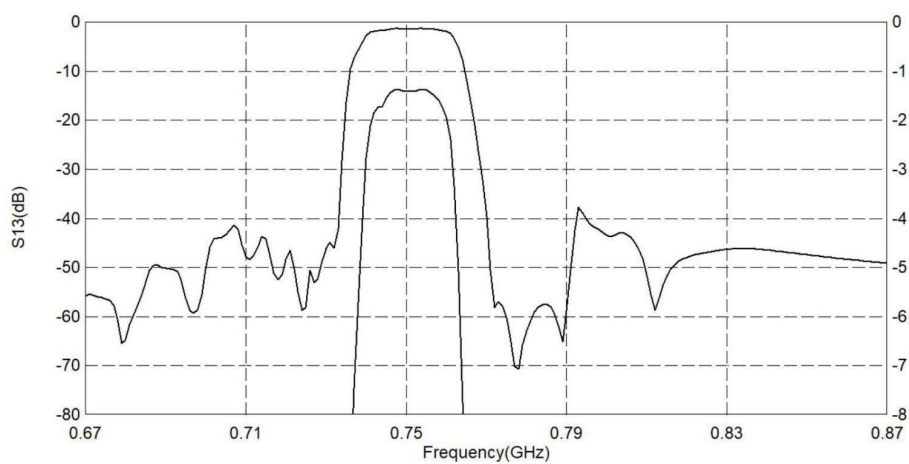


Figure 4 Electrical Characteristics: Ant to Rx.

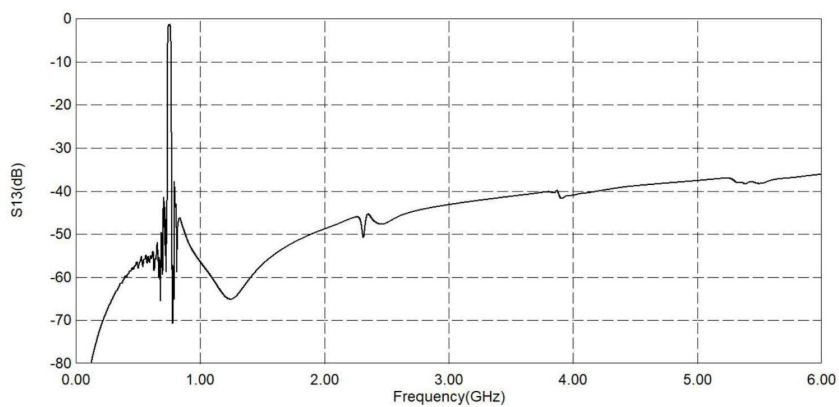


Figure 5 Electrical Characteristics: Tx to Rx.

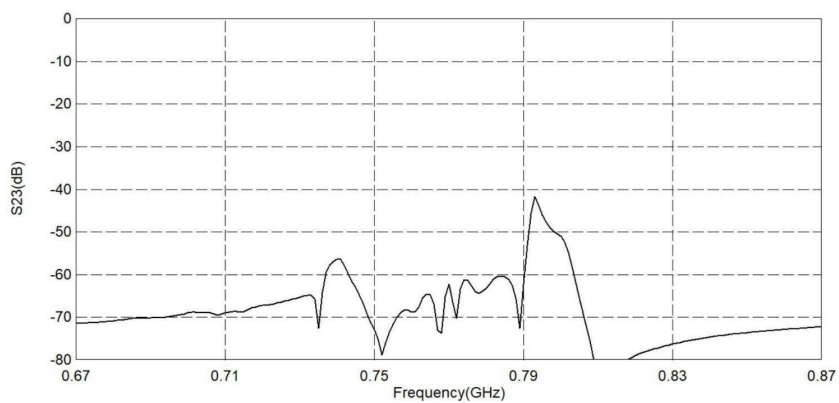
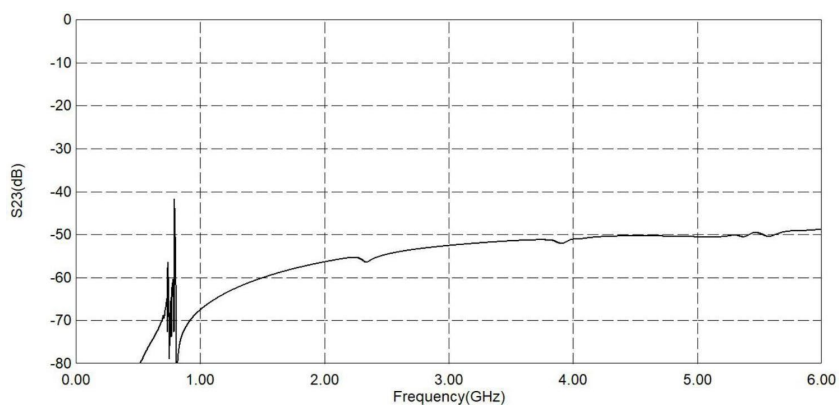
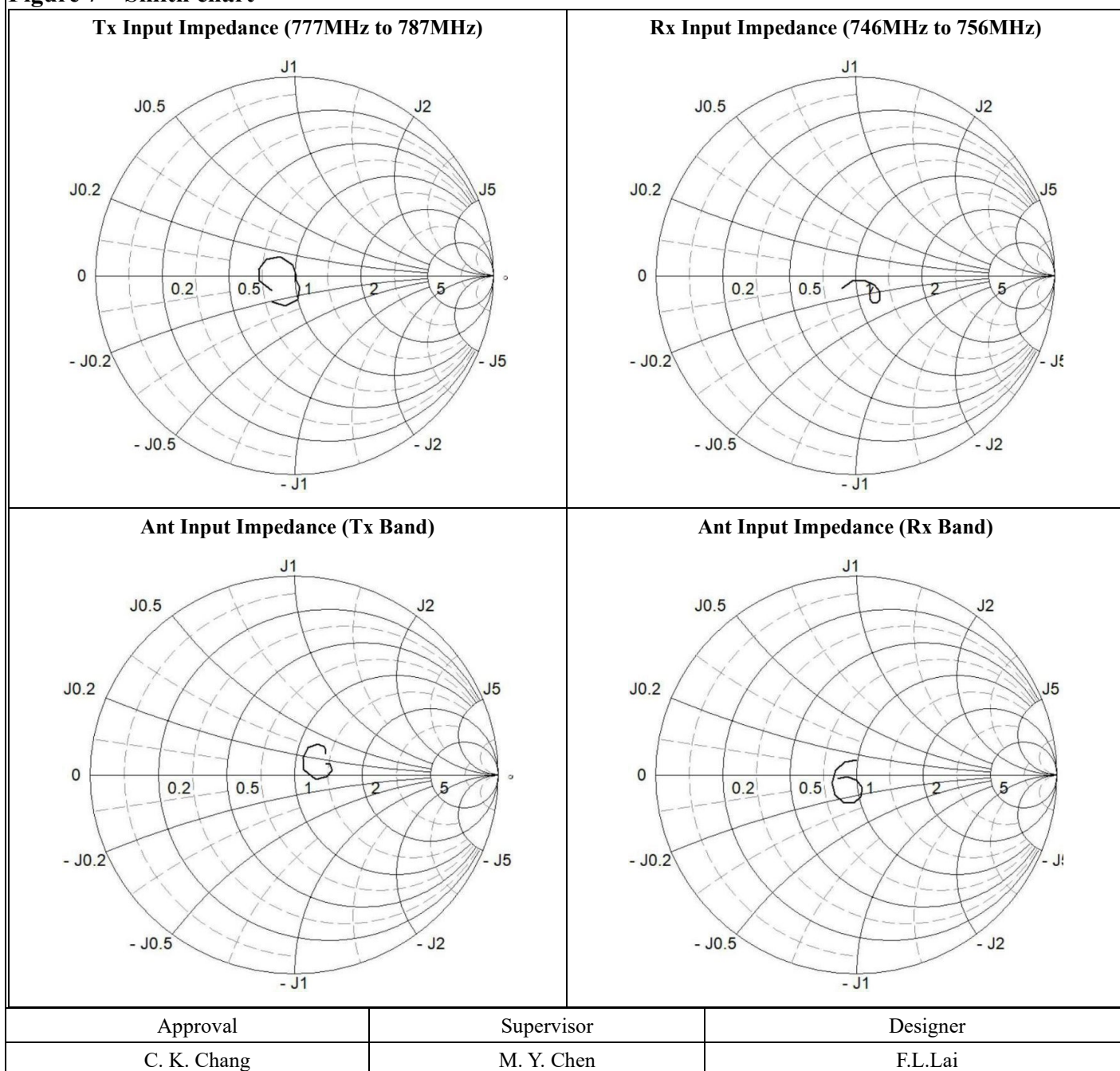
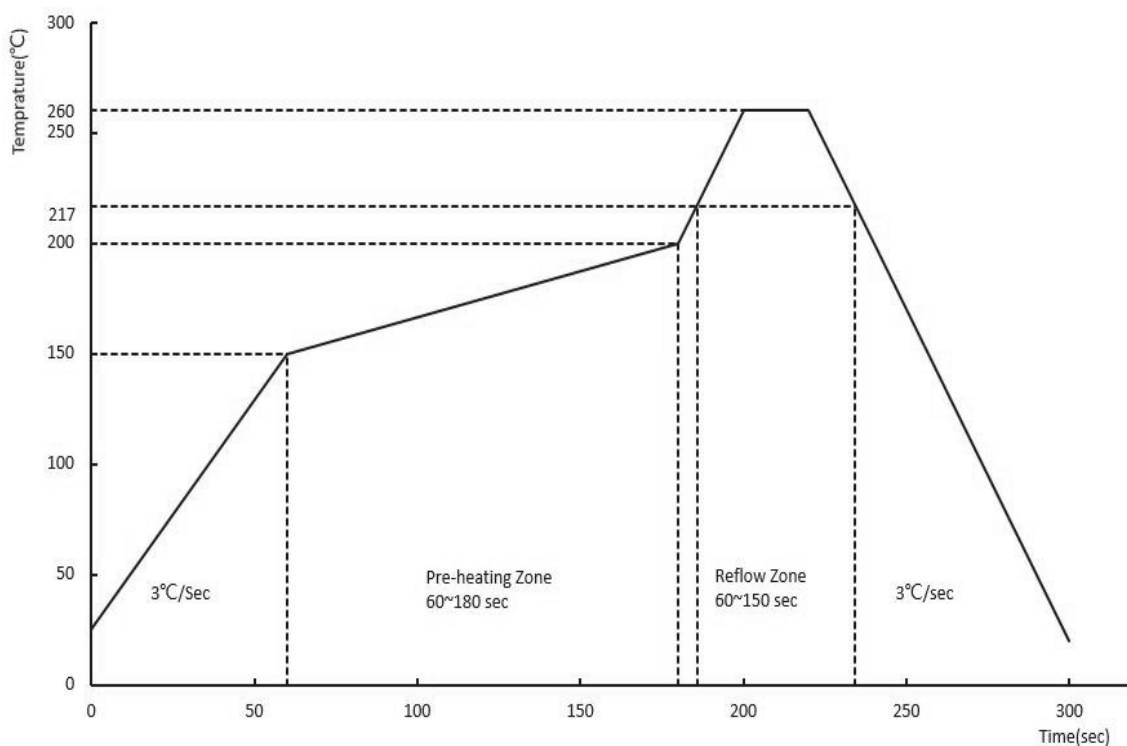


Figure 6 Electrical Characteristics: Tx to Rx.

Figure 7 Smith chart


Recommended SMT Solder Profile



Reliability

No.	Test item	Test condition	
1	Temperature Storage	Temperature: 85°C±2°C , Duration: 250h , Recovery time: 2h±0.5h Temperature: -40°C±3°C , Duration: 250h ,Recovery time: 2h±0.5h	
2	Humidity Test	Conditions: 60°C±2°C ,90~95%RH	Duration:250h
3	Thermal Shock	Heat cycle conditions: TA=-40°C±3°C, TB=85°C±2°C, t1=t2=30min, Switch time: ≤3min, Cycle time: 100 times, Recovery time: 2h±0.5h.	
4	Vibration Fatigue	Frequency of vibration:10~55Hz Directions: X,Y and Z	Amplitude:1.5mm Duration: 2h
5	Drop Test	Cycle time:10times	Height:1.0m
6	Solder Ability Test	Temperature:245°C±5°C Depth: DIP--2/3, SMD--1/5	Duration:3.0s--5.0s
7	Resistance to Soldering Heat	Thickness of PCB:1mm , Solder condition: 260°C±5°C , Duration:10±1s Temperature of Soldering Iron: 350°C±10°C, Duration: 3~4s, Recovery time : 2 ± 0.5h	